

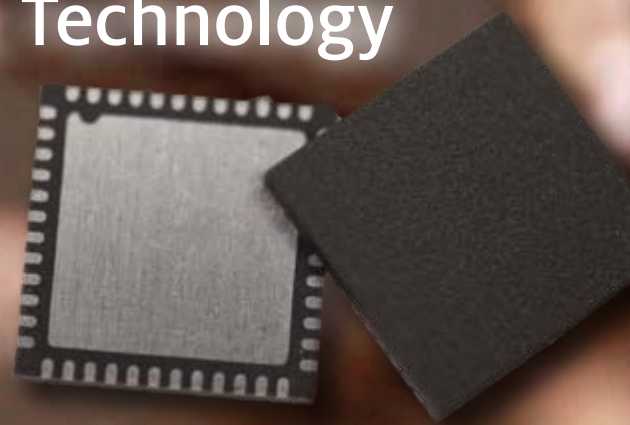
The background of the advertisement is a close-up photograph of a dark brown, grid-patterned substrate. In the center, a square area is highlighted, containing a large, intricate, silver-colored sintered structure that resembles a cross or a star with rounded ends. The lighting is dramatic, highlighting the metallic texture and the grid pattern.

**Ablestik**

# Ablestik SSP2000

## Introducing Silver Sintering Technology

Henkel Electronic's revolutionary silver (Ag) sintering technology enables high volume production of modern power packages in a process that does not require pressure. Henkel's Ag sintering capability has been designed into Ablestik SSP2000, a high reliability die attach material well-suited for use with power modules such as IGBTs and high power LED products.

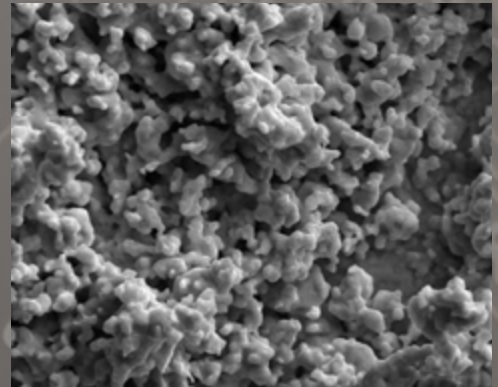
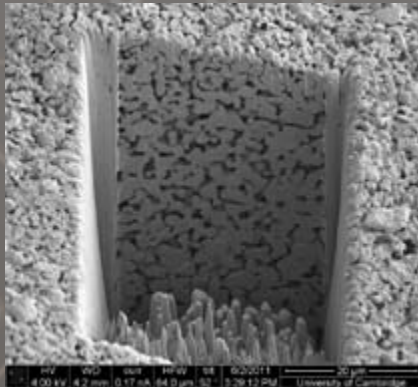
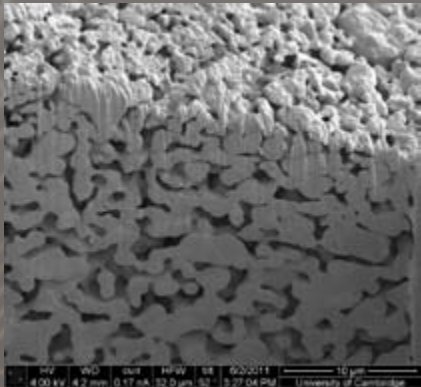
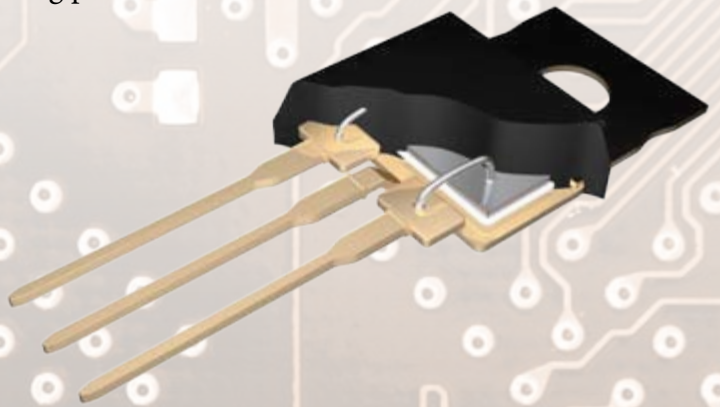
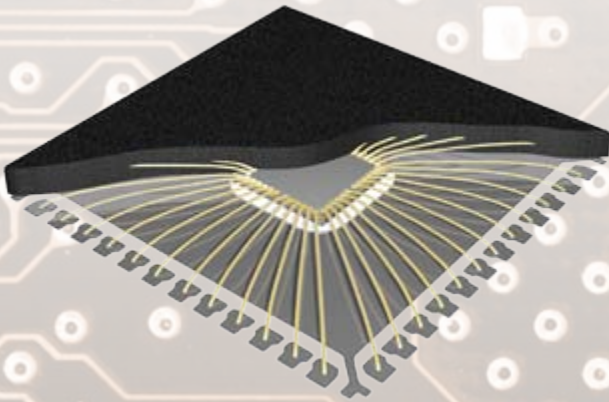


Excellence is our Passion

## Ablestik SSP2000 Silver Sintering Technology

### Key Benefits:

- Non-pressure approach
- High thermal and electrical performance
- Strong adhesion to metalized die and substrates
- Suitable for both Power modules and “standard” Power-Die Attach packages
- Non-pressure sintering compatible with current die attach equipment
- Significant improvement in thermal cycling over high lead solder
- Significant units/hr improvement over pressure sintering process



Samples of Sintered Density Between 75-80%

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